ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composit © Copyright 2005. IPC, 1 international and Pan-Am	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both Iev	nis docume vel parts, t	ent is a decla he declaration	aration on enco	of the substance ompasses all low	es within t ver level n	he manufactur naterials for w	rer listed it hich the m	tem. Note nanufactu	e: if the ite arer has en	em is an asser gineering res	bly with lower ponsibility.
1752-21.1					Form Type * Distribute						eneous Materi	ials and Mfg Information				
Supplier Informa	ation															
Company name*			Company unique ID			Unique ID Authority					Respons	Response Date*				
onsemi												2023-06-08				
Contact Name			Title - Contact			Phone - Contact*				Email - Contact*						
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Item		Mfr Item	Number Mfr Item Name				Effective D	Date	Version	Manufacturing Site			Weight*	U	ОМ	Unit Type
		SZNUP2115LT3G Low Capacitance I FlexRay Bus		ESD Protection Di	iode for	2023-06-08				8	3.13	m	g	Each		
Manufacturing P	Proccess Information	l														
Terminal Plating / Grid Array Material Termina			erminal Base A	se Alloy J-STD-020 MSL Rating		ating	Peak Process Body Temperature Max Tim		Time at Peak	ak Temperature Number of Reflow Cycles						
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		secon	ds 3					
Comments																
level 1 - maximum tir	ne at peak temperature d	luring sol	dering is 10-3	0 seconds												
For more information	n regarding material com	position j	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.16	mg	Supplier	Silicon (Si)	7440-21-3		0.16	mg
Lead Frame	2.92	mg	В	Nickel (Ni)	7440-02-0		1.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.4658	mg
			Supplier	Copper (Cu)	7440-50-8		0.3942	mg
Mold Compound-Black	4.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.49	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7105	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.185	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.49	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg